

## C1210C273M2TACTU

Aliases (C1210C273M2TAC7800)

**Specifications** 

Insulation Resistance

SMD Comm X8G HT150C, Ceramic, 0.027 uF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	40 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1210
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
Т	1.25mm +/-0.15mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

_	J.= / J.=	
W	2.5mm +/-0.2mm	Tole
Т	1.25mm +/-0.15mm	Vol
S	1.5mm MIN	Die
В	0.5mm +/-0.25mm	Ten
		Ten
Packaging Specifications		Car

Capacitance	0.027 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

37.037 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

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